What is claimed is:

1. A method of reducing delamination in an assembly, comprising

providing an assembly, the assembly comprising

an electronic device;

a substrate having a first surface and a second surface opposite the first surface, wherein the second surface of the substrate is disposed on the electronic device;

a barrier stack disposed on the first surface of the substrate; and

a weatherable sheet adjacent the barrier film opposite the substrate;

wherein the assembly is transmissive to visible and infrared light, and

limiting visible light exposure to parts of the assembly to maintain a peel force of 20 grams/inch or greater where the light is limited.

2. The assembly of claim 1 wherein the barrier stack comprises a polymer layer and an inorganic barrier layer.

3. The assembly of claim 2 wherein the inorganic barrier layer is an oxide layer.

4. The assembly of claim 1 wherein the multilayer film is transparent and flexible.

5. The assembly of claim 1 wherein the electronic device comprises an encapsulant layer.

6. The assembly of claim 1 wherein the electronic device comprises an edge seal material.

7. The assembly of claim 1 wherein the electronic device comprises a backsheet.

8. The assembly of claim 1 wherein the electronic device comprises a roof.

9. The method of claim 1 comprising a pressure sensitive adhesive layer ~~a pressure sensitive adhesive layer~~ between the weatherable sheet and the barrier stack.